



APPROVAL SHEET

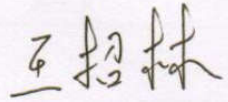
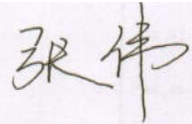
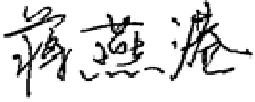
Approval Specification	Customer's Approval Certificate
TO:	Checked & Approved by:
Part No.:	Date:
Customer's Part No.:	Please return this copy as a certification of your approval

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Part No.	:	SF9010
Pages	:	7
Date	:	2013/4/17
Revision	:	1.0

Prepared by:	
Checked by:	
Approved by:	

History Record

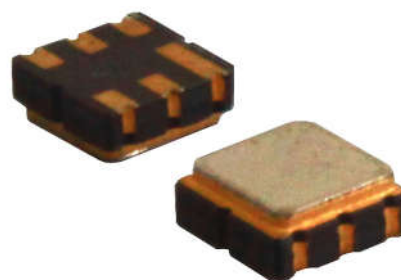
Date	Part No.	Version No.	Modify Content	Remark

Application

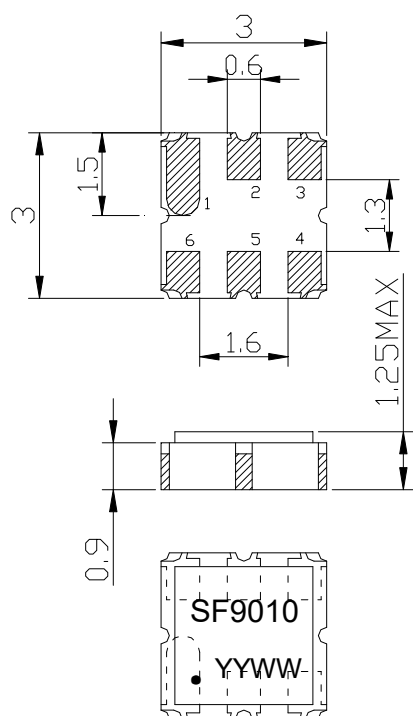
- Low-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable passband 26.0 MHz

Features

- Ceramic Package for **Surface Mounted Technology (SMT)**
- **RoHS** compatible
- Package size 3.00x3.00x1.25mm³
- Package Code DCC6C
- **Electrostatic Sensitive Device(ESD)**



Package Dimensions (Unit: mm)



Pin Configuration

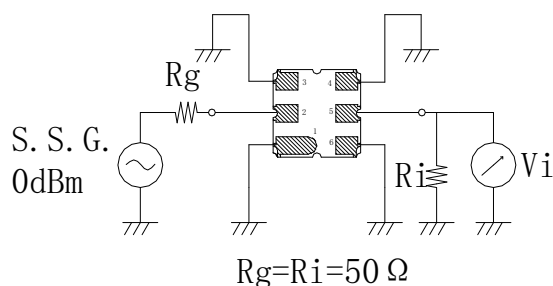
Pin No.	Description
2	Input
5	Output
1,3,4,6	Ground

Marking Description

S	Trademark
F	SAW Filter
9010	Part Number
●	Pin 1
* YYWW	Year Code & Week Code

*Fig: If the products produced in 06th week of 2012,
The year code & week code is 1206.
This item is optional.

Test Circuit (Bottom View)



Performance

Maximum Rating

Item		Value	Unit
DC Voltage	V_{DC}	5	V
Operation Temperature	T	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +85	°C
RF Power Dissipation	P	20	dBm

Electronic Characteristics

Test Temperature: $25^{\circ}\text{C} \pm 2^{\circ}\text{C}$

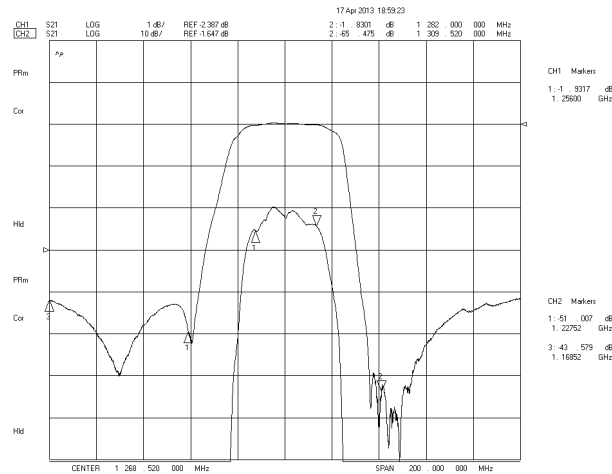
Terminating source impedance: 50Ω

Terminating load impedance: 50Ω

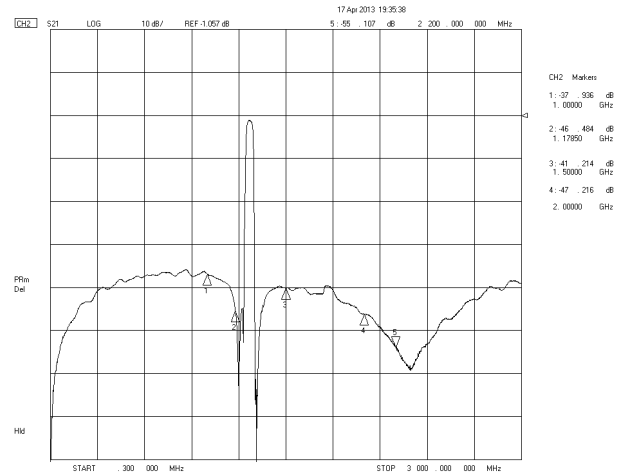
Item		Minimum	Typical	Maximum	Unit
Center Frequency	f_c		1268.52		MHz
Insertion Loss(min)	IL		1.4	1.7	dB
Insertion Loss 1256.00 - 1282.00MHz	IL		1.9	2.5	dB
Amplitude Ripple (p-p) 1256.00 - 1282.00MHz	Δa		0.6	1.0	dB
Group Delay Ripple 1256.00 - 1282.00MHz	GDR		20.0	40.0	ns
Absolute Attenuation	a				
DC - 1000.00 MHz		30.0	35.0		dB
1000.00 - 1178.50 MHz		30.0	35.0		dB
1208.52 MHz		40.0	45.0		dB
1227.52 MHz		40.0	43.0		dB
1309.52 MHz		45.0	50.0		dB
1328.52 MHz		40.0	45.0		dB
1500.00 - 2000.00 MHz		35.0	40.0		dB
2200.00 MHz		40.0	45.0		dB
2200.00 - 3000.00 MHz		30.0	35.0		dB
Input VSWR 1256.00 - 1282.00MHz			1.5:1	2.0:1	/
Output VSWR 1256.00 - 1282.00MHz			1.5:1	2.0:1	/

Frequency Characteristics

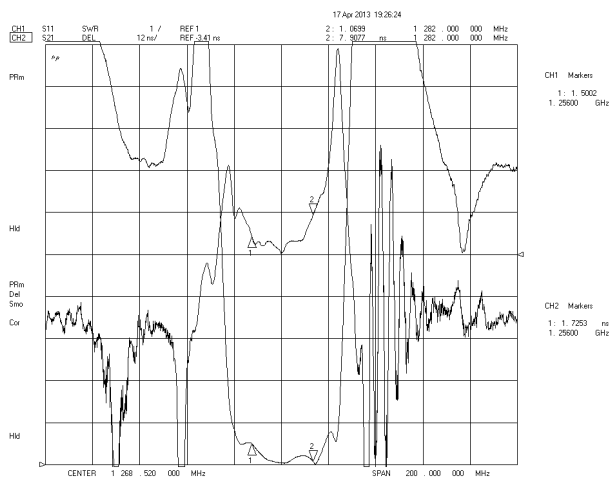
Frequency Response



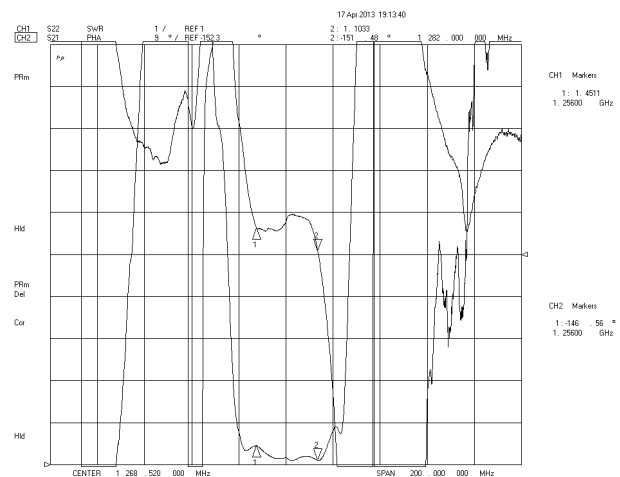
Frequency Response (wideband)



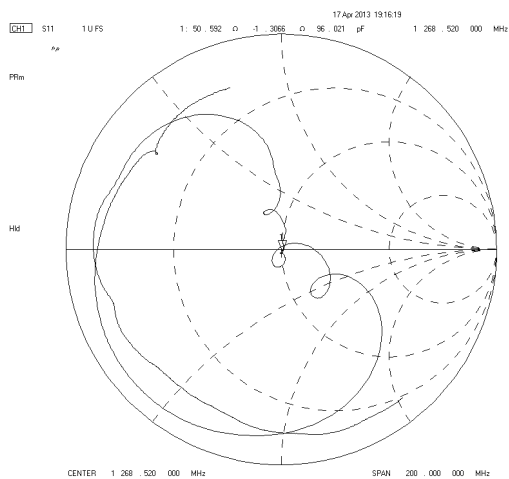
Delay Ripple & S11 VSWR



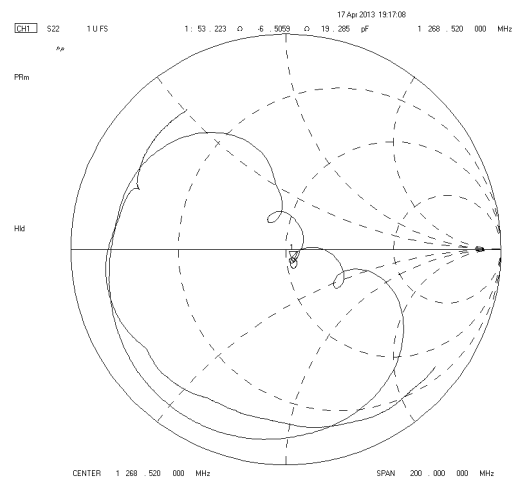
Phase Linearity & S22 VSWR



S11 Smith Chart



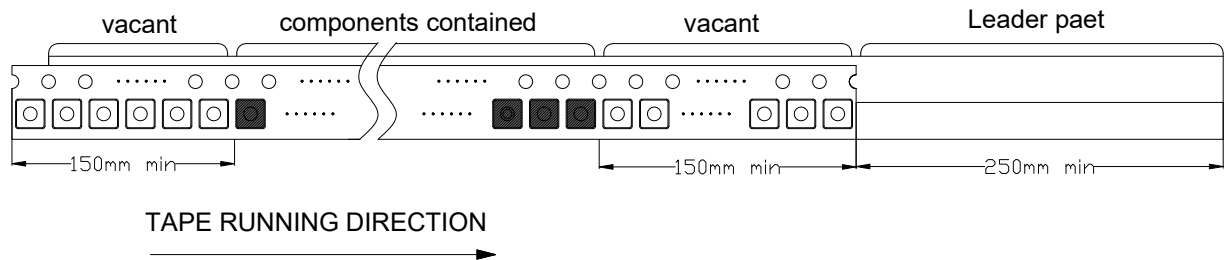
S22 Smith Chart



No.	Test item	Test condition
1	Temperature Storage	(1) Temperature: 85℃±2℃ , Duration: 250h , Recovery time: 2h±0.5h (2) Temperature: -55℃±3℃ , Duration: 250h ,Recovery time: 2h±0.5h
2	Humidity Test	Conditions: 60℃±2℃ , 90~95% RH Duration: 250h
3	Thermal Shock	Heat cycle conditions: TA=-55℃±3℃, TB=85℃±2℃, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.
4	Vibration Fatigue	Frequency of vibration: 10~55Hz Amplitude:1.5mm Directions: X,Y and Z Duration: 2h
5	Drop Test	Cycle time: 10 times Height: 1.0m
6	Solder Ability Test	Temperature: 245℃±5℃ Duration: 3.0s--5.0s Depth: DIP--2/3 , SMD--1/5
7	Resistance to Soldering Heat	(1) Thickness of PCB:1mm , Solder condition: 260℃±5℃ , Duration: 10±1s (2) Temperature of Soldering Iron: 350℃±10℃, Duration: 3~4s, Recovery time : 2 ± 0.5h

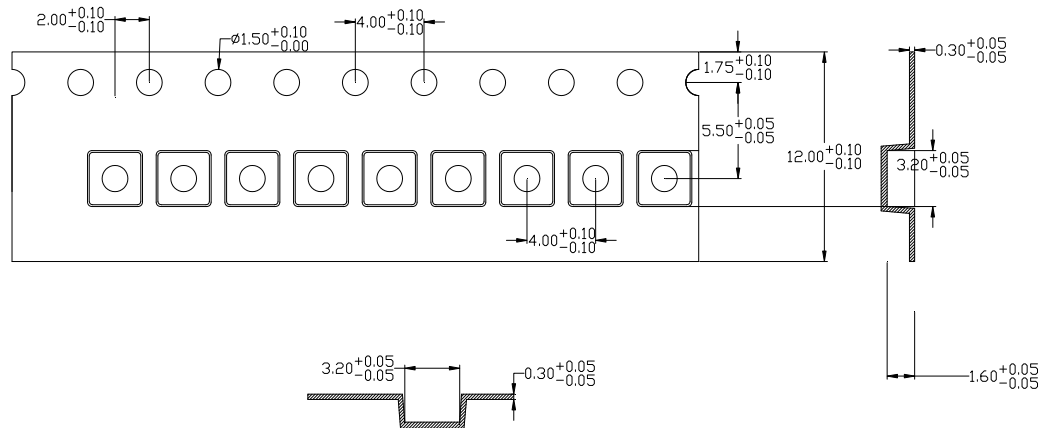
Packing Information

Carrier Tape



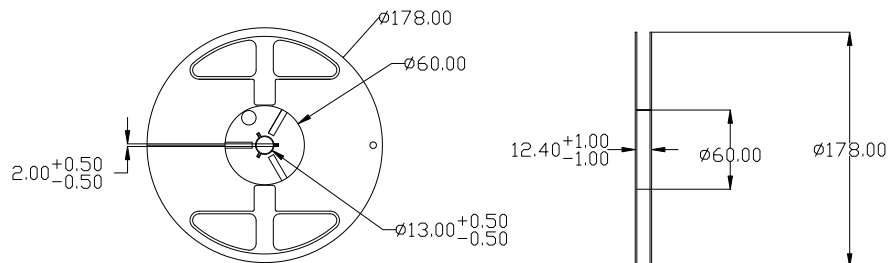
Reel Dimensions

Unit: mm



Outer Packing

Unit: mm



Notes

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.